

Special Issue

Future Information & Communication Engineering 2023

Message from the Guest Editors

This Special Issue will comprise selected papers from the ICFICE 2023, which was held at the NhaTrang Horizon Hotel of Vietnam on 10–13th January 2023. Following ICFICE 2023, we will organize a Special Issue, soliciting original research papers with all technical aspects of computer science, information, and communication engineering. Potential topics include, but are not limited to, the following:

- Communication System and Applications
- Networking and Security
- AI and Intelligent Information System
- Multimedia and Digital Convergence
- Semiconductor and Communication Services
- Biomedical Imaging and Engineering
- Ubiquitous Sensor Network
- Database and Internet Application
- IoT and Big Data
- IT Convergence Technology
- Industrial Session

Guest Editors

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Deadline for manuscript submissions

closed (31 December 2023)



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About the Journal

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

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